

## HIGH-SPEED QUAD DIGITAL ISOLATORS

Check for Samples: [ISO7240CF-Q1](#), [ISO7241C-Q1](#)

### FEATURES

- Qualified for Automotive Applications
- Selectable Failsafe Output (ISO7240CF)
- 25 and 150-Mbps Signaling Rate Options
  - Low Channel-to-Channel Output Skew;  
1 ns Max
  - Low Pulse-Width Distortion (PWD);  
2 ns Max
  - Low Jitter Content; 1 ns Typ at 150 Mbps
- Typical 25-Year Life at Rated Working Voltage (see application note [SLLA197](#) and [Figure 17](#))
- 4000- $V_{\text{peak}}$  Isolation, 560- $V_{\text{peak}}$   $V_{\text{IORM}}$ 
  - UL 1577, IEC 60747-5-2 (VDE 0884, Rev 2), IEC 61010-1, IEC 60950-1 and CSA Approved
- 4 kV ESD Protection
- Operate With 3.3-V or 5-V Supplies
- High Electromagnetic Immunity (see application report [SLLA181](#))
- $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$  Operating Range

### DESCRIPTION

The ISO7240, ISO7241 and ISO7242 are quad-channel digital isolators with multiple channel configurations and output enable functions. These devices have logic input and output buffers separated by TI's silicon dioxide ( $\text{SiO}_2$ ) isolation barrier. Used in conjunction with isolated power supplies, these devices block high voltage, isolate grounds, and prevent noise currents from entering the local ground and interfering with or damaging sensitive circuitry.

The ISO7240 has all four channels in the same direction while the ISO7241 has three channels the same direction and one channel in opposition. The ISO7242 has two channels in each direction.

The C option devices have TTL input thresholds and a noise-filter at the input that prevents transient pulses from being passed to the output of the device. The M option devices have CMOS  $V_{\text{CC}}/2$  input thresholds and do not have the input noise-filter or the additional propagation delay.

The ISO7240CF has an input disable function on pin 7, and a selectable high or low failsafe-output function with the CTRL pin (pin 10). The failsafe-output is a logic high when a logic-high is placed on the CTRL pin or it is left unconnected. If a logic-low signal is applied to the CTRL pin, the failsafe-output becomes a logic-low output state. The ISO7240CF input disable function prevents data from being passed across the isolation barrier to the output. When the inputs are disabled, the outputs are set by the CTRL pin.

These devices may be powered from either 3.3-V or 5-V supplies on either side in any 3.3-V / 3.3-V, 5-V / 5-V, 5-V / 3.3-V, or 3.3-V / 5-V combination. Note that the signal input pins are 5-V tolerant regardless of the voltage supply level being used.

These devices are characterized for operation over the ambient temperature range of  $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ .



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

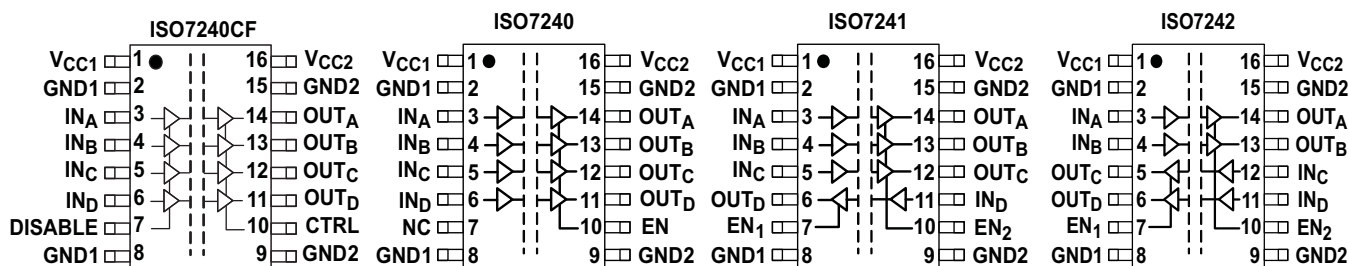


These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

**ORDERING INFORMATION<sup>(1)</sup>**

| T <sub>A</sub> | PACKAGE <sup>(2)</sup> |              | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|------------------------|--------------|-----------------------|------------------|
| -40°C to 125°C | SOIC – DW              | Reel of 2000 | ISO7240CFQDWRQ1       | ISO7240CFQ       |
|                |                        |              | ISO7240CQDWRQ1        | Product Preview  |
|                |                        |              | ISO7241CQDWRQ1        | ISO7241CQ        |
|                |                        |              | ISO7242CQDWRQ1        | ISO7242CQ        |

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).
- (2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).



**Table 1. ISO724xC Function Table<sup>(1)</sup>**

| INPUT V <sub>CC</sub> | OUTPUT V <sub>CC</sub> | INPUT (IN) | OUTPUT ENABLE (EN) | OUTPUT (OUT) |
|-----------------------|------------------------|------------|--------------------|--------------|
| PU                    | PU                     | H          | H or Open          | H            |
|                       |                        | L          | H or Open          | L            |
|                       |                        | X          | L                  | Z            |
|                       |                        | Open       | H or Open          | H            |
| PD                    | PU                     | X          | H or Open          | H            |
| PD                    | PU                     | X          | L                  | Z            |

(1) PU = Powered Up; PD = Powered Down ; X = Irrelevant; H = High Level; L = Low Level

**Table 2. ISO7240CF Function Table**

| V <sub>CC1</sub> | V <sub>CC2</sub> | DATA INPUT (IN) | DISABLE INPUT (DISABLE) | FAILSAFE CONTROL INPUT (CTRL) | DATA OUTPUT (OUT) |
|------------------|------------------|-----------------|-------------------------|-------------------------------|-------------------|
| PU               | PU               | H               | L or Open               | X                             | H                 |
| PU               | PU               | L               | L or Open               | X                             | L                 |
| X                | PU               | X               | H                       | H or Open                     | H                 |
| X                | PU               | X               | H                       | L                             | L                 |
| PD               | PU               | X               | X                       | H or Open                     | H                 |
| PD               | PU               | X               | X                       | L                             | L                 |

**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

|                 |   | VALUE                              | UNIT     |    |    |
|-----------------|---|------------------------------------|----------|----|----|
| V <sub>CC</sub> | Supply voltage <sup>(2)</sup> , V <sub>CC1</sub> , V <sub>CC2</sub> | –0.5 to 6                          | V        |    |    |
| V <sub>I</sub>  | Voltage at IN, OUT, EN, DISABLE, CTRL                               | –0.5 to 6                          | V        |    |    |
| I <sub>O</sub>  | Output current  | ±15                                | mA       |    |    |
| ESD             | Electrostatic discharge   | Human-Body Model                   | All pins | ±4 | kV |
|                 |   | Field-Induced-Charged Device Model |          | ±1 |    |
|                 |   | Machine Model                      | ±200     | V  |    |
| T <sub>J</sub>  | Maximum junction temperature  | 150                                | °C       |    |    |

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal and are peak voltage values.

**RECOMMENDED OPERATING CONDITIONS**

|                   |   | MIN  | TYP               | MAX             | UNIT |
|-------------------|---|------|-------------------|-----------------|------|
| V <sub>CC</sub>   | Supply voltage <sup>(1)</sup> , V <sub>CC1</sub> , V <sub>CC2</sub>                         | 3.15 |                   | 5.5             | V    |
| I <sub>OH</sub>   | High-level output current   |      |                   | 4               | mA   |
| I <sub>OL</sub>   | Low-level output current  | –4   |                   |                 | mA   |
| t <sub>ui</sub>   | Input pulse width   | 40   |                   |                 | ns   |
| 1/t <sub>ui</sub> | Signaling rate  | 0    | 30 <sup>(2)</sup> | 25              | Mbps |
| V <sub>IH</sub>   | High-level input voltage (IN, DISABLE, CTRL, EN)  | 2    |                   | V <sub>CC</sub> | V    |
| V <sub>IL</sub>   | Low-level input voltage (IN, DISABLE, CTRL, EN)   | 0    |                   | 0.8             | V    |
| T <sub>A</sub>    | Operating free-air temperature  | –40  |                   | 125             | °C   |
| H                 | External magnetic field-strength immunity per IEC 61000-4-8 and IEC 61000-4-9 certification |      |                   | 1000            | A/m  |

- (1) For the 5-V operation, V<sub>CC1</sub> or V<sub>CC2</sub> is specified from 4.5 V to 5.5 V.  
For the 3-V operation, V<sub>CC1</sub> or V<sub>CC2</sub> is specified from 3.15 V to 3.6 V.
- (2) Typical value at room temperature and well-regulated power supply.

**IEC 60747-5-2 INSULATION CHARACTERISTICS<sup>(1)</sup>**

over recommended operating conditions (unless otherwise noted)

| PARAMETER         | TEST CONDITIONS                    | SPECIFICATIONS  | UNIT             |   |
|-------------------|------------------------------------|---|------------------|---|
| V <sub>IORM</sub> | Maximum working insulation voltage | 560   | V                |   |
| V <sub>PR</sub>   | Input to output test voltage       | After Input/Output Safety Test Subgroup 2/3<br>V <sub>PR</sub> = V <sub>IORM</sub> × 1.2, t = 10 s,<br>Partial discharge < 5 pC | 672              | V |
|                   |                                    | Method a, V <sub>PR</sub> = V <sub>IORM</sub> × 1.6,<br>Type and sample test with t = 10 s,<br>Partial discharge < 5 pC         | 896              | V |
|                   |                                    | Method b1, V <sub>PR</sub> = V <sub>IORM</sub> × 1.875,<br>100 % Production test with t = 1 s,<br>Partial discharge < 5 pC      | 1050             | V |
| V <sub>IOTM</sub> | Transient overvoltage              | t = 60 s  | 4000             | V |
| R <sub>S</sub>    | Insulation resistance              | V <sub>IO</sub> = 500 V at T <sub>S</sub>   | >10 <sup>9</sup> | Ω |
|                   | Pollution degree                   |   | 2                |   |

- (1) Climatic Classification 40/125/21

**ELECTRICAL CHARACTERISTICS:  $V_{CC1}$  and  $V_{CC2}$  at 5-V<sup>(1)</sup> OPERATION**

, over recommended operating conditions (unless otherwise noted)

| PARAMETER                         |                                | TEST CONDITIONS                                     |   | MIN            | TYP | MAX  | UNIT  |
|-----------------------------------|--------------------------------|---|---|----------------|-----|------|-------|
| <b>SUPPLY CURRENT</b>             |                                |   |   |                |     |      |       |
| $I_{CC1}$                         | ISO7240C                       | Quiescent   | $V_I = V_{CC}$ or 0 V, All channels, no load,<br>EN <sub>2</sub> at 3 V                         |                | 1   | 3    | mA    |
|                                   |                                | 25 Mbps   |   |                | 7   | 10.5 |       |
|                                   | ISO7241C                       | Quiescent   | $V_I = V_{CC}$ or 0 V, All channels, no load,<br>EN <sub>1</sub> at 3 V, EN <sub>2</sub> at 3 V |                | 6.5 | 11   | mA    |
|                                   |                                | 25 Mbps   |   |                | 12  | 18   |       |
|                                   | ISO7242C                       | Quiescent   | $V_I = V_{CC}$ or 0 V, All channels, no load,<br>EN <sub>1</sub> at 3 V, EN <sub>2</sub> at 3 V |                | 10  | 16   | mA    |
|                                   |                                | 25 Mbps   |   |                | 15  | 24   |       |
| $I_{CC2}$                         | ISO7240C                       | Quiescent   | $V_I = V_{CC}$ or 0 V, All channels, no load,<br>EN <sub>2</sub> at 3 V                         |                | 15  | 22   | mA    |
|                                   |                                | 25 Mbps   |   |                | 17  | 25   |       |
|                                   | ISO7241C                       | Quiescent   | $V_I = V_{CC}$ or 0 V, All channels, no load,<br>EN <sub>1</sub> at 3 V, EN <sub>2</sub> at 3 V |                | 13  | 20   | mA    |
|                                   |                                | 25 Mbps   |   |                | 18  | 28   |       |
|                                   | ISO7242C                       | Quiescent   | $V_I = V_{CC}$ or 0 V, All channels, no load,<br>EN <sub>1</sub> at 3 V, EN <sub>2</sub> at 3 V |                | 10  | 16   | mA    |
|                                   |                                | 25 Mbps   |   |                | 15  | 24   |       |
| <b>ELECTRICAL CHARACTERISTICS</b> |                                |   |   |                |     |      |       |
| $I_{OFF}$                         | Sleep mode output current      | EN at 0 V, Single channel                           |   |                | 0   |      | μA    |
| $V_{OH}$                          | High-level output voltage      | $I_{OH} = -4$ mA, See <a href="#">Figure 1</a>      |   | $V_{CC} - 0.8$ |     |      | V     |
|                                   |                                | $I_{OH} = -20$ μA, See <a href="#">Figure 1</a>     |   | $V_{CC} - 0.1$ |     |      |       |
| $V_{OL}$                          | Low-level output voltage       | $I_{OL} = 4$ mA, See <a href="#">Figure 1</a>       |   |                |     | 0.4  | V     |
|                                   |                                | $I_{OL} = 20$ μA, See <a href="#">Figure 1</a>      |   |                |     | 0.1  |       |
| $V_{I(HYS)}$                      | Input voltage hysteresis       |   |   |                | 150 |      | mV    |
| $I_{IH}$                          | High-level input current       | IN from 0 V to $V_{CC}$                             |   |                |     | 10   | μA    |
| $I_{IL}$                          | Low-level input current        |   |   |                | -10 |      |       |
| $C_I$                             | Input capacitance to ground    | IN at $V_{CC}$ , $V_I = 0.4 \sin(4E6\pi t)$         |   |                | 2   |      | pF    |
| CMTI                              | Common-mode transient immunity | $V_I = V_{CC}$ or 0 V, See <a href="#">Figure 5</a> |   | 25             | 50  |      | kV/μs |

- (1) For the 5-V operation,  $V_{CC1}$  or  $V_{CC2}$  is specified from 4.5 V to 5.5 V.  
For the 3-V operation,  $V_{CC1}$  or  $V_{CC2}$  is specified from 3.15 V to 3.6 V.

**SWITCHING CHARACTERISTICS:  $V_{CC1}$  and  $V_{CC2}$  at 5-V OPERATION**

over recommended operating conditions (unless otherwise noted)

| PARAMETER             |   | TEST CONDITIONS              | MIN | TYP | MAX | UNIT    |
|-----------------------|---|------------------------------|-----|-----|-----|---------|
| $t_{PLH}$ , $t_{PHL}$ | Propagation delay   | See <a href="#">Figure 1</a> | 18  |     | 45  | ns      |
| PWD                   | Pulse-width distortion <sup>(1)</sup> $ t_{PHL} - t_{PLH} $ |                              |     |     | 5   |         |
| $t_{sk(pp)}$          | Part-to-part skew <sup>(2)</sup>                            |                              |     |     | 8   | ns      |
| $t_{sk(o)}$           | Channel-to-channel output skew <sup>(3)</sup>               | ISO7240C, ISO7241C           |     |     | 3   | ns      |
|                       |   | ISO7242C                     |     |     | 4   |         |
| $t_r$                 | Output signal rise time                                     | See <a href="#">Figure 1</a> |     | 2   |     | ns      |
| $t_f$                 | Output signal fall time                                     |                              |     | 2   |     |         |
| $t_{PHZ}$             | Propagation delay, high-level-to-high-impedance output      | See <a href="#">Figure 2</a> |     | 15  | 25  | ns      |
| $t_{PZH}$             | Propagation delay, high-impedance-to-high-level output      |                              |     | 15  | 25  |         |
| $t_{PLZ}$             | Propagation delay, low-level-to-high-impedance output       |                              |     | 15  | 25  |         |
| $t_{PZL}$             | Propagation delay, high-impedance-to-low-level output       |                              |     | 15  | 25  |         |
| $t_{fs}$              | Failsafe output delay time from input power loss            | See <a href="#">Figure 3</a> |     | 12  |     | $\mu$ s |
| $t_{wake}$            | Wake time from input disable                                | See <a href="#">Figure 4</a> |     | 15  |     | $\mu$ s |

- (1) Also referred to as pulse skew.
- (2)  $t_{sk(pp)}$  is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.
- (3)  $t_{sk(o)}$  is the skew between specified outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical specified loads.

**ELECTRICAL CHARACTERISTICS:  $V_{CC1}$  at 5-V,  $V_{CC2}$  at 3.3-V<sup>(1)</sup> OPERATION**

over recommended operating conditions (unless otherwise noted)

| PARAMETER                         |                                | TEST CONDITIONS                                     |  | MIN            | TYP            | MAX         | UNIT    |
|-----------------------------------|--------------------------------|---|--|----------------|----------------|-------------|---------|
| <b>SUPPLY CURRENT</b>             |                                |   |  |                |                |             |         |
| $I_{CC1}$                         | ISO7240C                       | Quiescent   | $V_1 = V_{CC}$ or 0 V, All channels, no load, $EN_2$ at 3 V                |                | 1              | 3           | mA      |
|                                   |                                | 25 Mbps   |  |                | 7              | 10.5        |         |
|                                   | ISO7241C                       | Quiescent   | $V_1 = V_{CC}$ or 0 V, All channels, no load, $EN_1$ at 3 V, $EN_2$ at 3 V |                | 6.5            | 11          | mA      |
|                                   |                                | 25 Mbps   |  |                | 12             | 18          |         |
|                                   | ISO7242C                       | Quiescent   | $V_1 = V_{CC}$ or 0 V, All channels, no load, $EN_1$ at 3 V, $EN_2$ at 3 V |                | 10             | 16          | mA      |
|                                   |                                | 25 Mbps   |  |                | 15             | 24          |         |
| $I_{CC2}$                         | ISO7240C                       | Quiescent   | $V_1 = V_{CC}$ or 0 V, All channels, no load, $EN_2$ at 3 V                |                | 9.5            | 15          | mA      |
|                                   |                                | 25 Mbps   |  |                | 10.5           | 17          |         |
|                                   | ISO7241C                       | Quiescent   | $V_1 = V_{CC}$ or 0 V, All channels, no load, $EN_1$ at 3 V, $EN_2$ at 3 V |                | 8              | 13          | mA      |
|                                   |                                | 25 Mbps   |  |                | 11.5           | 18          |         |
|                                   | ISO7242C                       | Quiescent   | $V_1 = V_{CC}$ or 0 V, All channels, no load, $EN_1$ at 3 V, $EN_2$ at 3 V |                | 6              | 10          | mA      |
|                                   |                                | 25 Mbps   |  |                | 9              | 14          |         |
| <b>ELECTRICAL CHARACTERISTICS</b> |                                |   |  |                |                |             |         |
| $I_{OFF}$                         | Sleep mode output current      | EN at 0 V, Single channel                           |  |                | 0              |             | $\mu$ A |
| $V_{OH}$                          | High-level output voltage      | $I_{OH} = -4$ mA, See <a href="#">Figure 1</a>      | ISO7240  | $V_{CC} - 0.4$ |                | V           |         |
|                                   |                                |   | ISO724x (5-V side)   | $V_{CC} - 0.8$ |                |             |         |
|                                   |                                |   | $I_{OH} = -20$ $\mu$ A, See <a href="#">Figure 1</a>                       |                | $V_{CC} - 0.1$ |             |         |
| $V_{OL}$                          | Low-level output voltage       | $I_{OL} = 4$ mA, See <a href="#">Figure 1</a>       |  | 0.4            |                | V           |         |
|                                   |                                | $I_{OL} = 20$ $\mu$ A, See <a href="#">Figure 1</a> |  | 0.1            |                |             |         |
| $V_{I(HYS)}$                      | Input voltage hysteresis       |   |  | 150            |                | mV          |         |
| $I_{IH}$                          | High-level input current       | IN from 0 V to $V_{CC}$                             |  | 10             |                | $\mu$ A     |         |
| $I_{IL}$                          | Low-level input current        |   |  |                |                |             | -10     |
| $C_1$                             | Input capacitance to ground    | IN at $V_{CC}$ , $V_1 = 0.4 \sin(4E6\pi t)$         |  | 2              |                | pF          |         |
| CMTI                              | Common-mode transient immunity | $V_1 = V_{CC}$ or 0 V, See <a href="#">Figure 5</a> |  | 25             | 50             | kV/ $\mu$ s |         |

(1) For the 5-V operation,  $V_{CC1}$  or  $V_{CC2}$  is specified from 4.5 V to 5.5 V.  
For the 3-V operation,  $V_{CC1}$  or  $V_{CC2}$  is specified from 3.15 V to 3.6 V.

**SWITCHING CHARACTERISTICS:  $V_{CC1}$  at 5-V,  $V_{CC2}$  at 3.3-V OPERATION**

over recommended operating conditions (unless otherwise noted)

| PARAMETER             |   | TEST CONDITIONS              | MIN | TYP | MAX | UNIT    |
|-----------------------|---|------------------------------|-----|-----|-----|---------|
| $t_{PLH}$ , $t_{PHL}$ | Propagation delay   | See <a href="#">Figure 1</a> | 20  |     | 50  | ns      |
| PWD                   | Pulse-width distortion <sup>(1)</sup> $ t_{PHL} - t_{PLH} $ | ISO7240C, ISO7241C           |     |     | 3   |         |
|                       |   | ISO7242C                     |     |     | 4   |         |
| $t_{sk(pp)}$          | Part-to-part skew <sup>(2)</sup>                            |                              |     |     | 10  | ns      |
| $t_{sk(o)}$           | Channel-to-channel output skew <sup>(3)</sup>               | ISO7240C, ISO7241C           |     |     | 3   | ns      |
|                       |   | ISO7242C                     |     |     | 4   |         |
| $t_r$                 | Output signal rise time                                     | See <a href="#">Figure 1</a> |     | 2   |     | ns      |
| $t_f$                 | Output signal fall time                                     |                              |     | 2   |     |         |
| $t_{PHZ}$             | Propagation delay, high-level-to-high-impedance output      | See <a href="#">Figure 2</a> |     | 15  | 25  | ns      |
| $t_{PZH}$             | Propagation delay, high-impedance-to-high-level output      |                              |     | 15  | 25  |         |
| $t_{PLZ}$             | Propagation delay, low-level-to-high-impedance output       |                              |     | 15  | 25  |         |
| $t_{PZL}$             | Propagation delay, high-impedance-to-low-level output       |                              |     | 15  | 25  |         |
| $t_{fs}$              | Failsafe output delay time from input power loss            | See <a href="#">Figure 3</a> |     | 18  |     | $\mu$ s |
| $t_{wake}$            | Wake time from input disable                                | See <a href="#">Figure 4</a> |     | 15  |     | $\mu$ s |

(1) Also known as pulse skew

 (2)  $t_{sk(pp)}$  is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

 (3)  $t_{sk(o)}$  is the skew between specified outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical specified loads.

**ELECTRICAL CHARACTERISTICS:  $V_{CC1}$  at 3.3-V,  $V_{CC2}$  at 5-V<sup>(1)</sup> OPERATION**

over recommended operating conditions (unless otherwise noted)

| PARAMETER                         |                                | TEST CONDITIONS                                     |  | MIN            | TYP            | MAX | UNIT  |
|-----------------------------------|--------------------------------|---|--|----------------|----------------|-----|-------|
| <b>SUPPLY CURRENT</b>             |                                |   |  |                |                |     |       |
| $I_{CC1}$                         | ISO7240C                       | Quiescent   | $V_I = V_{CC}$ or 0 V, All channels, no load, EN <sub>2</sub> at 3 V                         |                | 0.5            | 1   | mA    |
|                                   |                                | 25 Mbps   |  |                | 3              | 5   |       |
|                                   | ISO7241C                       | Quiescent   | $V_I = V_{CC}$ or 0 V, All channels, no load, EN <sub>1</sub> at 3 V, EN <sub>2</sub> at 3 V |                | 4              | 7   | mA    |
|                                   |                                | 25 Mbps   |  |                | 6.5            | 11  |       |
|                                   | ISO7242C                       | Quiescent   | $V_I = V_{CC}$ or 0 V, All channels, no load, EN <sub>1</sub> at 3 V, EN <sub>2</sub> at 3 V |                | 6              | 10  | mA    |
|                                   |                                | 25 Mbps   |  |                | 9              | 14  |       |
| $I_{CC2}$                         | ISO7240C                       | Quiescent   | $V_I = V_{CC}$ or 0 V, All channels, no load, EN <sub>2</sub> at 3 V                         |                | 15             | 22  | mA    |
|                                   |                                | 25 Mbps   |  |                | 17             | 25  |       |
|                                   | ISO7241C                       | Quiescent   | $V_I = V_{CC}$ or 0 V, All channels, no load, EN <sub>1</sub> at 3 V, EN <sub>2</sub> at 3 V |                | 13             | 20  | mA    |
|                                   |                                | 25 Mbps   |  |                | 18             | 28  |       |
|                                   | ISO7242C                       | Quiescent   | $V_I = V_{CC}$ or 0 V, All channels, no load, EN <sub>1</sub> at 3 V, EN <sub>2</sub> at 3 V |                | 10             | 16  | mA    |
|                                   |                                | 25 Mbps   |  |                | 15             | 24  |       |
| <b>ELECTRICAL CHARACTERISTICS</b> |                                |   |  |                |                |     |       |
| $I_{OFF}$                         | Sleep mode output current      | EN at 0 V, Single channel                           |  |                | 0              |     | μA    |
| $V_{OH}$                          | High-level output voltage      | $I_{OH} = -4$ mA, See <a href="#">Figure 1</a>      | ISO7240  |                | $V_{CC} - 0.4$ |     | V     |
|                                   |                                |   | ISO724x (5-V side)   |                | $V_{CC} - 0.8$ |     |       |
|                                   |                                | $I_{OH} = -20$ μA, See <a href="#">Figure 1</a>     |  | $V_{CC} - 0.1$ |                |     |       |
| $V_{OL}$                          | Low-level output voltage       | $I_{OL} = 4$ mA, See <a href="#">Figure 1</a>       |  |                |                | 0.4 | V     |
|                                   |                                | $I_{OL} = 20$ μA, See <a href="#">Figure 1</a>      |  |                |                | 0.1 |       |
| $V_{I(HYS)}$                      | Input voltage hysteresis       |   |  |                | 150            |     | mV    |
| $I_{IH}$                          | High-level input current       | IN from 0 V to $V_{CC}$                             |  |                |                | 10  | μA    |
| $I_{IL}$                          | Low-level input current        |   |  |                |                | -10 |       |
| $C_I$                             | Input capacitance to ground    | IN at $V_{CC}$ , $V_I = 0.4 \sin(4E6\pi t)$         |  |                | 2              |     | pF    |
| CMTI                              | Common-mode transient immunity | $V_I = V_{CC}$ or 0 V, See <a href="#">Figure 5</a> |  |                | 25             | 50  | kV/μs |

- (1) For the 5-V operation,  $V_{CC1}$  or  $V_{CC2}$  is specified from 4.5 V to 5.5 V.  
For the 3-V operation,  $V_{CC1}$  or  $V_{CC2}$  is specified from 3.15 V to 3.6 V.



**SWITCHING CHARACTERISTICS:  $V_{CC1}$  at 3.3-V and  $V_{CC2}$  at 5-V OPERATION**

over recommended operating conditions (unless otherwise noted)

| PARAMETER                |   | TEST CONDITIONS              | MIN | TYP | MAX | UNIT    |
|--------------------------|---|------------------------------|-----|-----|-----|---------|
| $t_{PLH}$ ,<br>$t_{PHL}$ | Propagation delay   | See <a href="#">Figure 1</a> | 20  |     | 51  | ns      |
| PWD                      | Pulse-width distortion <sup>(1)</sup> $ t_{PHL} - t_{PLH} $ | See <a href="#">Figure 1</a> |     |     | 3   |         |
|                          |   | ISO7240C,<br>ISO7241C        |     |     | 4   |         |
|                          |   | ISO7242C                     |     |     | 4   |         |
| $t_{sk(pp)}$             | Part-to-part skew <sup>(2)</sup>                            |                              |     |     | 10  | ns      |
| $t_{sk(o)}$              | Channel-to-channel output skew <sup>(3)</sup>               | ISO7240C, ISO7241C           |     |     | 3   | ns      |
|                          |   | ISO7242C                     |     |     | 4   |         |
| $t_r$                    | Output signal rise time                                     | See <a href="#">Figure 1</a> |     | 2   |     | ns      |
| $t_f$                    | Output signal fall time                                     |                              |     | 2   |     |         |
| $t_{PHZ}$                | Propagation delay,<br>high-level-to-high-impedance output   | See <a href="#">Figure 2</a> |     | 15  | 25  | ns      |
| $t_{PZH}$                | Propagation delay,<br>high-impedance-to-high-level output   |                              |     | 15  | 25  |         |
| $t_{PLZ}$                | Propagation delay, low-level-to-high-impedance<br>output    |                              |     | 15  | 25  |         |
| $t_{PZL}$                | Propagation delay, high-impedance-to-low-level<br>output    |                              |     | 15  | 25  |         |
| $t_{fs}$                 | Failsafe output delay time from input power loss            | See <a href="#">Figure 3</a> |     | 12  |     | $\mu$ s |
| $t_{wake}$               | Wake time from input disable                                | See <a href="#">Figure 4</a> |     | 15  |     | $\mu$ s |

(1) Also known as pulse skew

 (2)  $t_{sk(pp)}$  is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

 (3)  $t_{sk(o)}$  is the skew between specified outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical specified loads.

## ELECTRICAL CHARACTERISTICS: $V_{CC1}$ and $V_{CC2}$ at 3.3 V<sup>(1)</sup> OPERATION

over recommended operating conditions (unless otherwise noted)

| PARAMETER                         |                                | TEST CONDITIONS                                     |   | MIN            | TYP | MAX | UNIT  |
|-----------------------------------|--------------------------------|---|---|----------------|-----|-----|-------|
| <b>SUPPLY CURRENT</b>             |                                |   |   |                |     |     |       |
| $I_{CC1}$                         | ISO7240C                       | Quiescent   | $V_1 = V_{CC}$ or 0 V, all channels, no load,<br>EN <sub>2</sub> at 3 V                         | 0.5            |     | 1   | mA    |
|                                   |                                | 25 Mbps   |   | 3              |     | 5   |       |
|                                   | ISO7241C                       | Quiescent   | $V_1 = V_{CC}$ or 0 V, all channels, no load,<br>EN <sub>1</sub> at 3 V, EN <sub>2</sub> at 3 V | 4              |     | 7   | mA    |
|                                   |                                | 25 Mbps   |   | 6.5            |     | 11  |       |
|                                   | ISO7242C                       | Quiescent   | $V_1 = V_{CC}$ or 0 V, all channels, no load,<br>EN <sub>1</sub> at 3 V, EN <sub>2</sub> at 3 V | 6              |     | 10  |       |
|                                   |                                | 25 Mbps   |   | 9              |     | 14  |       |
| $I_{CC2}$                         | ISO7240C                       | Quiescent   | $V_1 = V_{CC}$ or 0 V, all channels, no load,<br>EN <sub>2</sub> at 3 V                         | 9.5            |     | 15  | mA    |
|                                   |                                | 25 Mbps   |   | 10.5           |     | 17  |       |
|                                   | ISO7241C                       | Quiescent   | $V_1 = V_{CC}$ or 0 V, all channels, no load,<br>EN <sub>1</sub> at 3 V, EN <sub>2</sub> at 3 V | 8              |     | 13  | mA    |
|                                   |                                | 25 Mbps   |   | 11.5           |     | 18  |       |
|                                   | ISO7242C                       | Quiescent   | $V_1 = V_{CC}$ or 0 V, all channels, no load,<br>EN <sub>1</sub> at 3 V, EN <sub>2</sub> at 3 V | 6              |     | 10  |       |
|                                   |                                | 25 Mbps   |   | 9              |     | 14  |       |
| <b>ELECTRICAL CHARACTERISTICS</b> |                                |   |   |                |     |     |       |
| $I_{OFF}$                         | Sleep mode output current      | EN at 0 V, single channel                           |   | 0              |     |     | μA    |
| $V_{OH}$                          | High-level output voltage      | $I_{OH} = -4$ mA, See <a href="#">Figure 1</a>      |   | $V_{CC} - 0.4$ |     |     | V     |
|                                   |                                | $I_{OH} = -20$ μA, See <a href="#">Figure 1</a>     |   | $V_{CC} - 0.1$ |     |     |       |
| $V_{OL}$                          | Low-level output voltage       | $I_{OL} = 4$ mA, See <a href="#">Figure 1</a>       |   |                |     | 0.4 | V     |
|                                   |                                | $I_{OL} = 20$ μA, See <a href="#">Figure 1</a>      |   |                |     | 0.1 |       |
| $V_{I(HYS)}$                      | Input voltage hysteresis       |   |   | 150            |     |     | mV    |
| $I_{IH}$                          | High-level input current       | IN from 0 V or $V_{CC}$                             |   |                |     | 10  | μA    |
| $I_{IL}$                          | Low-level input current        |   |   |                |     | -10 |       |
| $C_I$                             | Input capacitance to ground    | IN at $V_{CC}$ , $V_1 = 0.4 \sin(4E6\pi t)$         |   |                |     | 2   | pF    |
| CMTI                              | Common-mode transient immunity | $V_1 = V_{CC}$ or 0 V, See <a href="#">Figure 5</a> |   | 25             | 50  |     | kV/μs |

- (1) For the 5-V operation,  $V_{CC1}$  or  $V_{CC2}$  is specified from 4.5 V to 5.5 V.  
For the 3-V operation,  $V_{CC1}$  or  $V_{CC2}$  is specified from 3.15 V to 3.6 V.

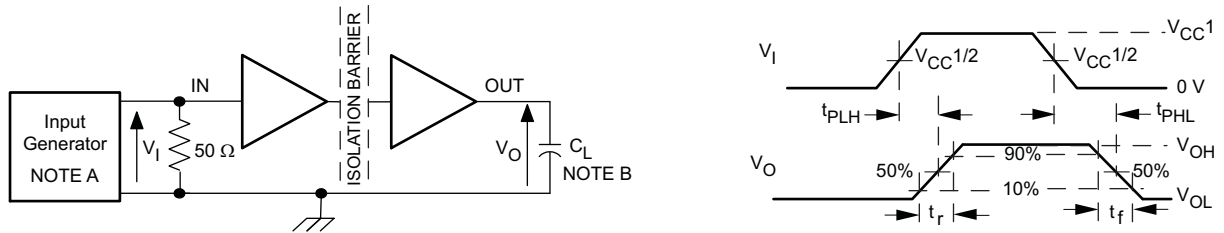
**SWITCHING CHARACTERISTICS:  $V_{CC1}$  and  $V_{CC2}$  at 3.3-V OPERATION**

over recommended operating conditions (unless otherwise noted)

| PARAMETER                |   | TEST CONDITIONS    |                       | MI<br>N | TY<br>P | MAX | UNIT    |
|--------------------------|---|--------------------|-----------------------|---------|---------|-----|---------|
| $t_{PLH}$ ,<br>$t_{PHL}$ | Propagation delay   | See Figure 1       |                       | 25      |         | 56  | ns      |
| PWD                      | Pulse-width distortion $ t_{PHL} - t_{PLH} ^{(1)}$        |                    |                       |         |         | 4   |         |
| $t_{sk(pp)}$             | Part-to-part skew <sup>(2)</sup>                          |                    |                       |         |         | 10  | ns      |
| $t_{sk(o)}$              | Channel-to-channel output skew <sup>(3)</sup>             | ISO7240C, ISO7241C |                       |         |         | 3.5 | ns      |
|                          |   | ISO7242C           |                       |         |         | 4   |         |
| $t_r$                    | Output signal rise time                                   | See Figure 1       |                       |         |         | 2   | ns      |
| $t_f$                    | Output signal fall time                                   |                    |                       |         |         | 2   | ns      |
| $t_{PHZ}$                | Propagation delay,<br>high-level-to-high-impedance output | See Figure 2       | ISO7240C,<br>ISO7241C | 15      |         | 20  | ns      |
|                          |   |                    | ISO7242C              | 15      |         | 25  |         |
| $t_{PZH}$                | Propagation delay,<br>high-impedance-to-high-level output |                    | ISO7240C,<br>ISO7241C | 15      |         | 20  |         |
|                          |   |                    | ISO7242C              | 15      |         | 25  |         |
| $t_{PLZ}$                | Propagation delay, low-level-to-high-impedance<br>output  |                    | ISO7240C,<br>ISO7241C | 15      |         | 20  |         |
|                          |   |                    | ISO7242C              | 15      |         | 25  |         |
| $t_{PZL}$                | Propagation delay, high-impedance-to-low-level<br>output  |                    | ISO7240C,<br>ISO7241C | 15      |         | 20  |         |
|                          |   |                    | ISO7242C              | 15      |         | 25  |         |
| $t_{fs}$                 | Failsafe output delay time from input power<br>loss       | See Figure 3       |                       |         |         | 18  | $\mu$ s |
| $t_{wake}$               | Wake time from input disable                              | See Figure 4       |                       |         |         | 15  | $\mu$ s |

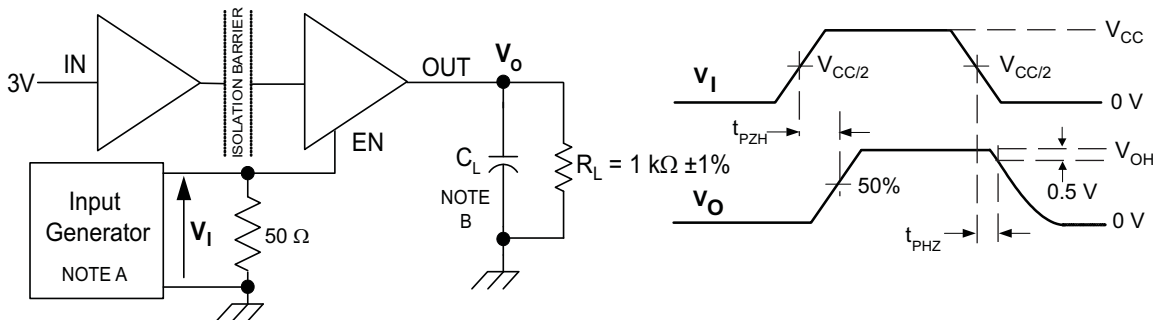
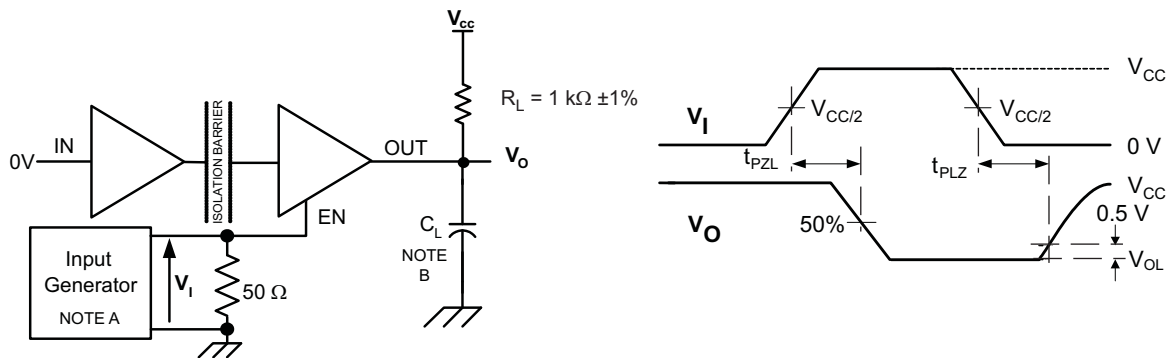
- (1) Also referred to as pulse skew.
- (2)  $t_{sk(pp)}$  is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.
- (3)  $t_{sk(o)}$  is the skew between specified outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical specified loads.

PARAMETER MEASUREMENT INFORMATION



- A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 50 kHz, 50% duty cycle,  $t_r \leq 3$  ns,  $t_f \leq 3$  ns,  $Z_O = 50\Omega$ .
- B.  $C_L = 15$  pF and includes instrumentation and fixture capacitance within ±20%.

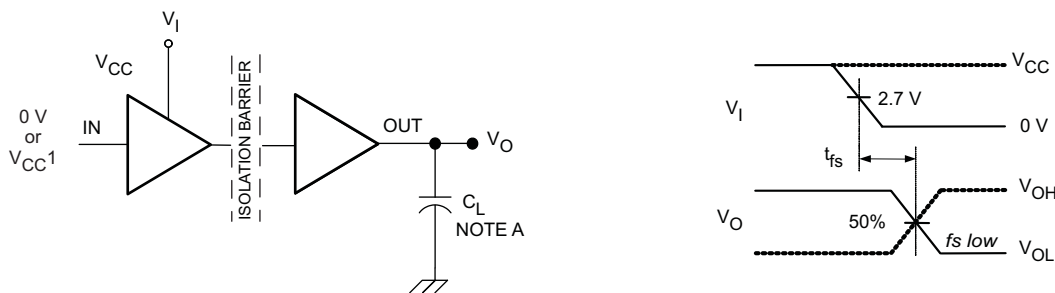
Figure 1. Switching Characteristic Test Circuit and Voltage Waveforms



- A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 50 kHz, 50% duty cycle,  $t_r \leq 3$  ns,  $t_f \leq 3$  ns,  $Z_O = 50\Omega$ .
- B.  $C_L = 15$  pF and includes instrumentation and fixture capacitance within ±20%.

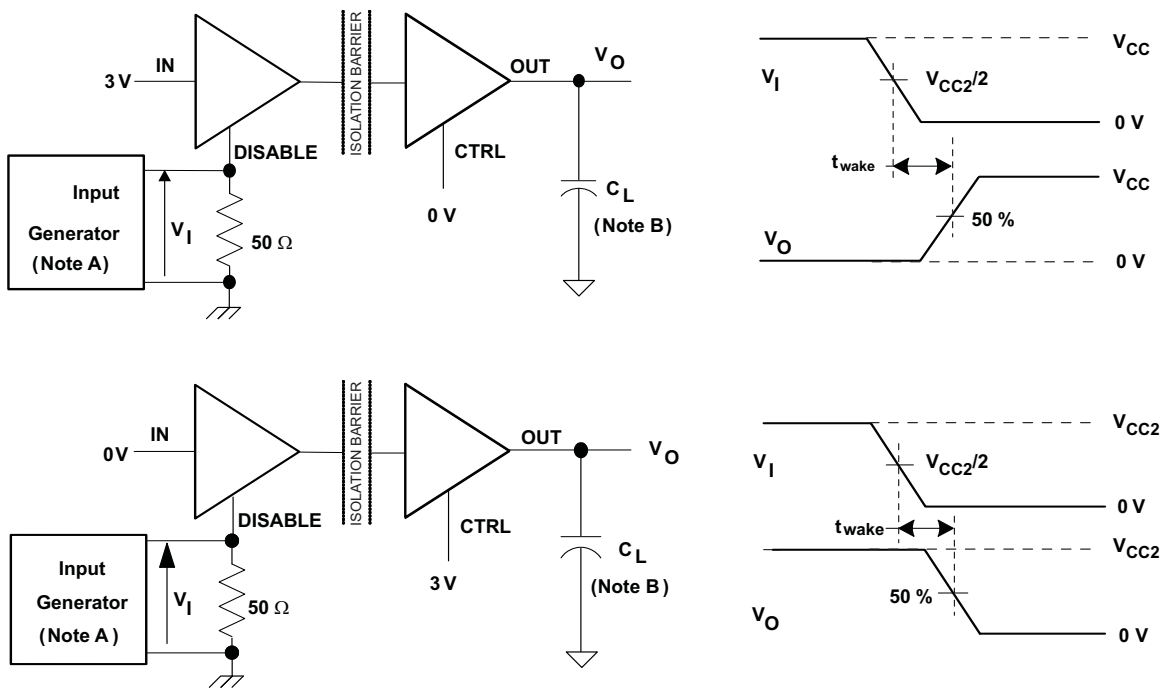
Figure 2. Enable/Disable Propagation Delay Time Test Circuit and Waveform

PARAMETER MEASUREMENT INFORMATION (continued)



- A.  $C_L = 15 \text{ pF}$  and includes instrumentation and fixture capacitance within  $\pm 20\%$ .
- B. The input pulse is supplied by a generator having the following characteristics:  $\text{PRR} \leq 50 \text{ kHz}$ , 50% duty cycle,  $t_r \leq 3 \text{ ns}$ ,  $t_f \leq 3 \text{ ns}$ ,  $Z_0 = 50 \Omega$ .

Figure 3. Failsafe Delay Time Test Circuit and Voltage Waveforms

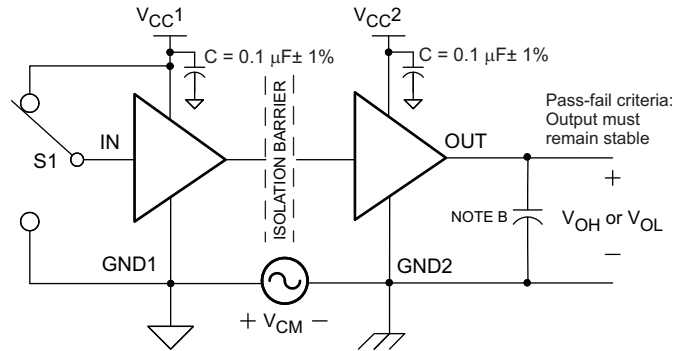


NOTE: Which ever test yields the longest time is used in this data sheet

- A. Whichever test yields the longest time is used in this data sheet.

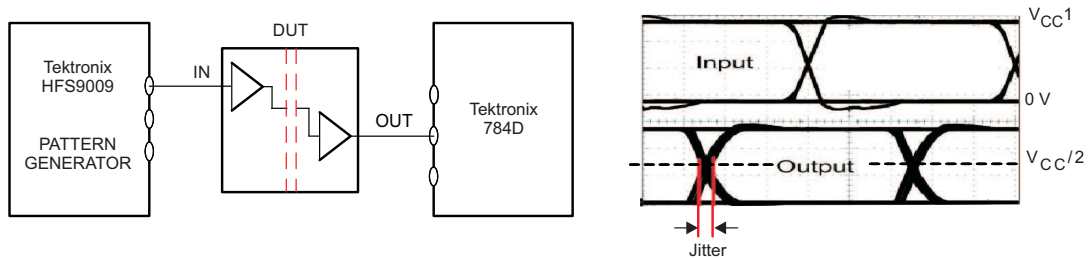
Figure 4. Wake Time From Input Disable Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION (continued)



- A.  $C_L = 15 \text{ pF}$  and includes instrumentation and fixture capacitance within  $\pm 20\%$ .
- B. The input pulse is supplied by a generator having the following characteristics:  $\text{PRR} \leq 50 \text{ kHz}$ , 50% duty cycle,  $t_r \leq 3 \text{ ns}$ ,  $t_f \leq 3 \text{ ns}$ ,  $Z_O = 50 \Omega$ .

Figure 5. Common-Mode Transient Immunity Test Circuit and Voltage Waveform



NOTE: PRBS bit pattern run length is  $2^{16} - 1$ . Transition time is 800 ps. NRZ data input has no more than five consecutive 1s or 0s.

Figure 6. Peak-to-Peak Eye-Pattern Jitter Test Circuit and Voltage Waveform

## DEVICE INFORMATION

### PACKAGE CHARACTERISTICS

| PARAMETER       |  | TEST CONDITIONS   | MIN   | TYP               | MAX | UNIT |
|-----------------|--|---|-------|-------------------|-----|------|
| L(I01)          | Minimum air gap (Clearance)                      | Shortest terminal-to-terminal distance through air  | 8.34  |                   |     | mm   |
| L(I02)          | Minimum external tracking (Creepage)             | Shortest terminal-to-terminal distance across the package surface   | 8.1   |                   |     | mm   |
| C <sub>TI</sub> | Tracking resistance (comparative tracking index) | DIN IEC 60112/VDE 0303 Part 1   | ≥ 175 |                   |     | V    |
|                 | Minimum Internal Gap (Internal Clearance)        | Distance through the insulation   | 0.008 |                   |     | mm   |
| R <sub>IO</sub> | Isolation resistance                             | Input to output, V <sub>IO</sub> = 500 V, all pins on each side of the barrier tied together creating a two-terminal device |       | >10 <sup>12</sup> |     | Ω    |
| C <sub>IO</sub> | Barrier capacitance Input to output              | V <sub>I</sub> = 0.4 sin (4E6πt)  |       | 2                 |     | pF   |
| C <sub>I</sub>  | Input capacitance to ground                      | V <sub>I</sub> = 0.4 sin (4E6πt)  |       | 2                 |     | pF   |

### IEC 60664-1 RATINGS TABLE

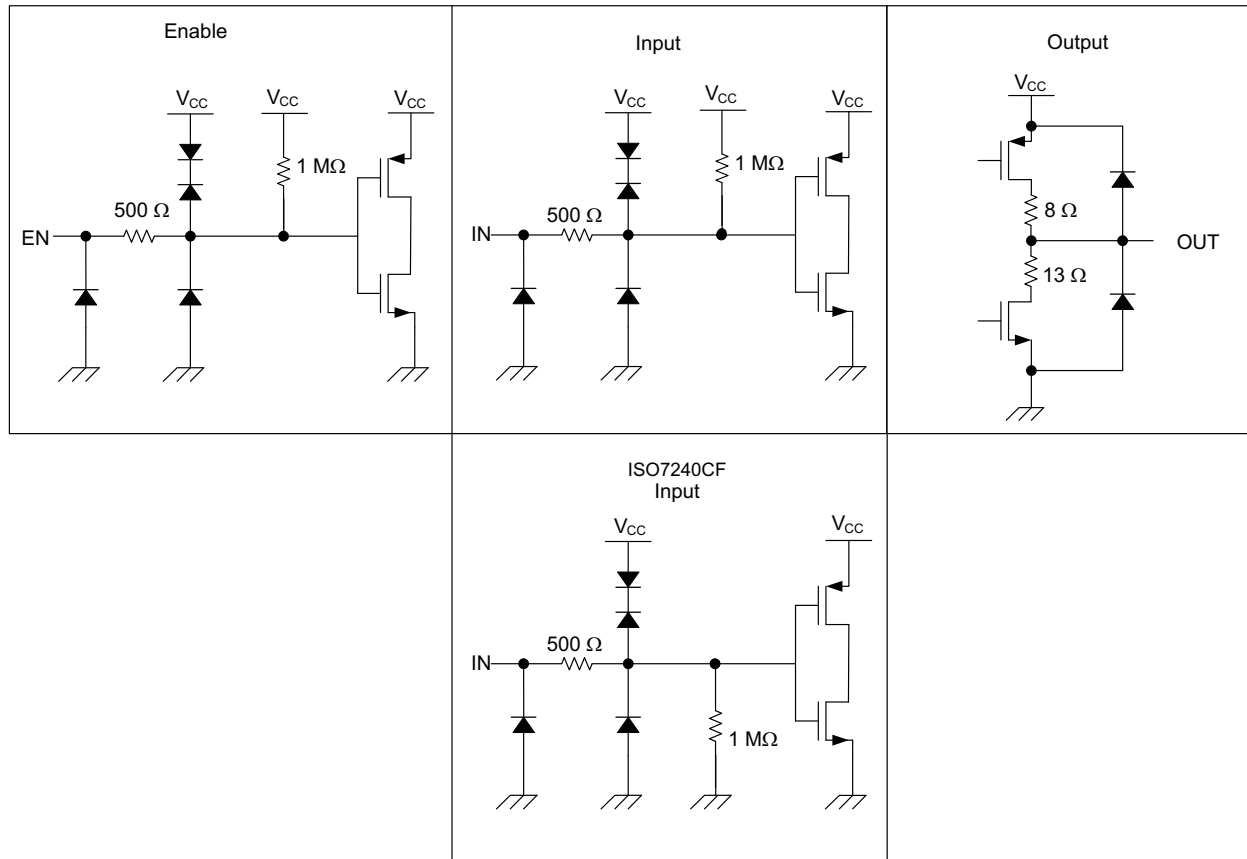
| PARAMETER                   | TEST CONDITIONS               | SPECIFICATION |
|-----------------------------|-------------------------------|---------------|
| Basic isolation group       | Material group                | IIIa          |
| Installation classification | Rated mains voltage ≤150 VRMS | I-IV          |
|                             | Rated mains voltage ≤300 VRMS | I-III         |

### REGULATORY INFORMATION

| VDE                                  | CSA  | UL   |
|--------------------------------------|--|--|
| Certified according to IEC 60747-5-2 | Approved under CSA Component Acceptance Notice | Recognized under 1577 Component Recognition Program <sup>(1)</sup> |
| File Number: 40016131                | File Number: 1698195                           | File Number: E181974   |

(1) Production tested ≥ 3000 Vrms for 1 second in accordance with UL 1577.

## DEVICE I/O SCHEMATICS



## THERMAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

| PARAMETER  | TEST CONDITIONS   | MIN | TYP  | MAX | UNIT |
|--|---|-----|------|-----|------|
| $\theta_{JA}$ Junction-to-air                      | Low-K Thermal Resistance <sup>(1)</sup>   |     | 168  |     | °C/W |
|  | High-K Thermal Resistance   |     | 96.1 |     |      |
| $\theta_{JB}$ Junction-to-Board Thermal Resistance |   |     | 61   |     | °C/W |
| $\theta_{JC}$ Junction-to-Case Thermal Resistance  |   |     | 48   |     | °C/W |
| $P_D$ Device Power Dissipation                     | $V_{CC1} = V_{CC2} = 5.5$ V, $T_J = 150^\circ$ C, $C_L = 15$ pF, Input a 50% duty cycle square wave |     |      | 220 | mW   |

(1) Tested in accordance with the Low-K or High-K thermal metric definitions of EIA/JESD51-3 for leaded surface mount packages.



TYPICAL CHARACTERISTIC CURVES

ISO7240C RMS SUPPLY CURRENT  
VS  
SIGNALING RATE

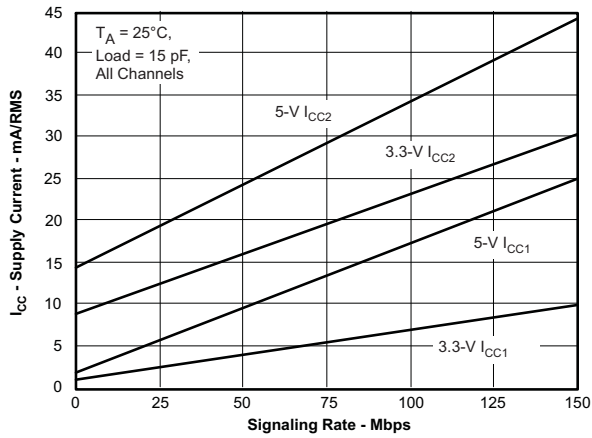


Figure 7.

ISO7241C RMS SUPPLY CURRENT  
VS  
SIGNALING RATE

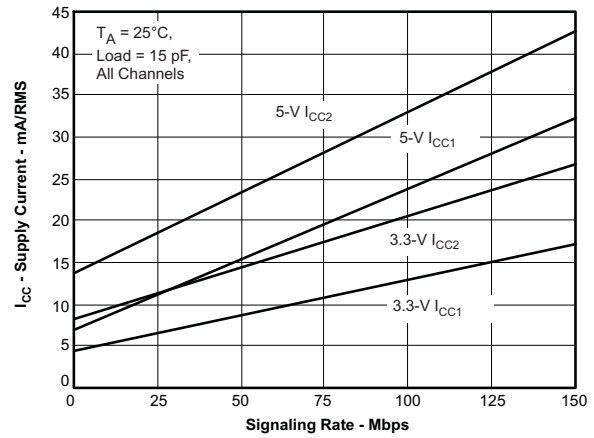


Figure 8.

ISO7242C RMS SUPPLY CURRENT  
VS  
SIGNALING RATE

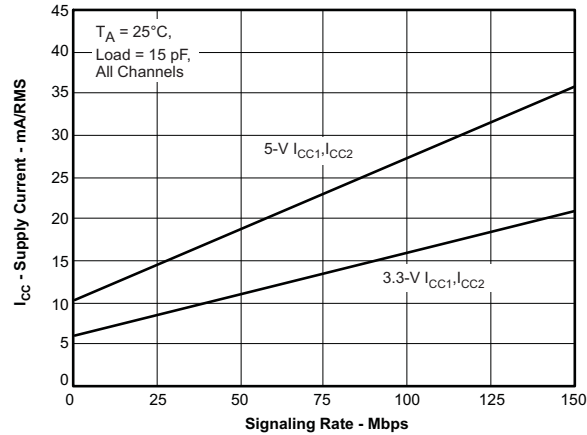


Figure 9.

PROPAGATION DELAY  
VS  
FREE-AIR TEMPERATURE

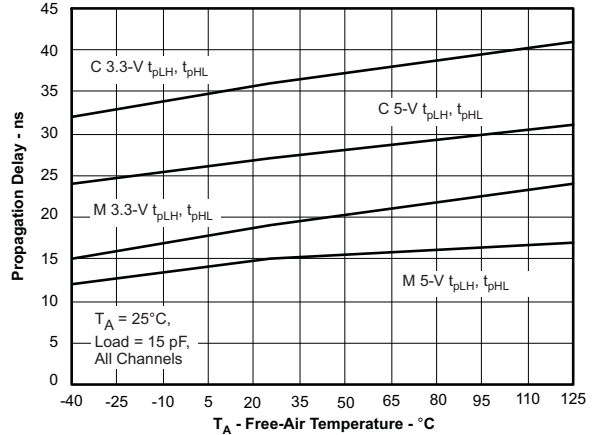


Figure 10.

**TYPICAL CHARACTERISTIC CURVES (continued)**

**INPUT VOLTAGE THRESHOLD  
 vs  
 FREE-AIR TEMPERATURE**

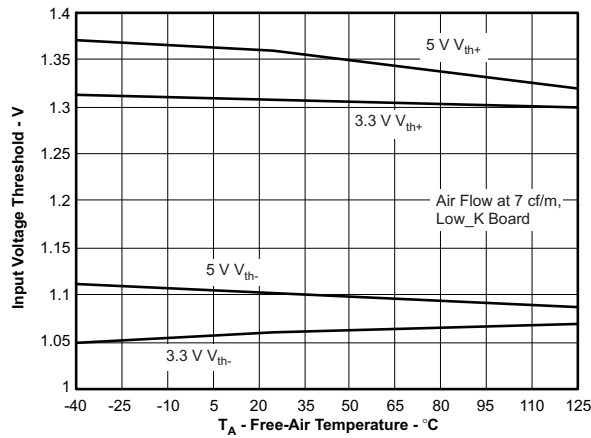


Figure 11.

**V<sub>CC1</sub> FAILSAFE THRESHOLD  
 vs  
 FREE-AIR TEMPERATURE**

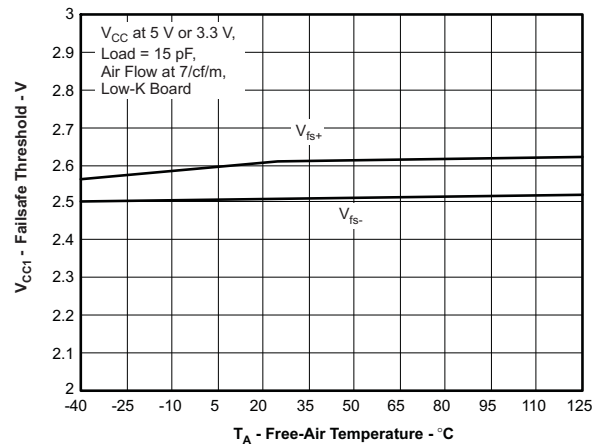


Figure 12.

**HIGH-LEVEL OUTPUT CURRENT  
 vs  
 HIGH-LEVEL OUTPUT VOLTAGE**

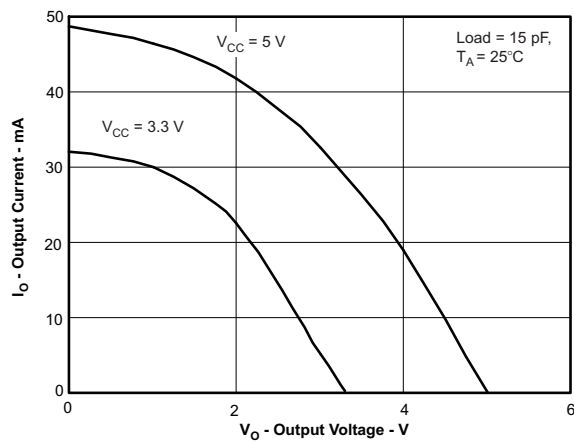


Figure 13.

**LOW-LEVEL OUTPUT CURRENT  
 vs  
 LOW-LEVEL OUTPUT VOLTAGE**

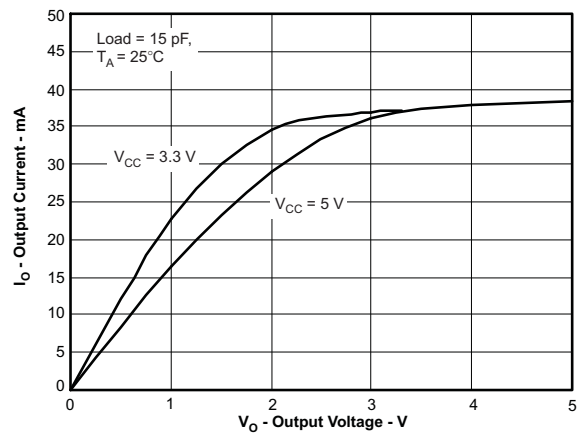


Figure 14.

APPLICATION INFORMATION

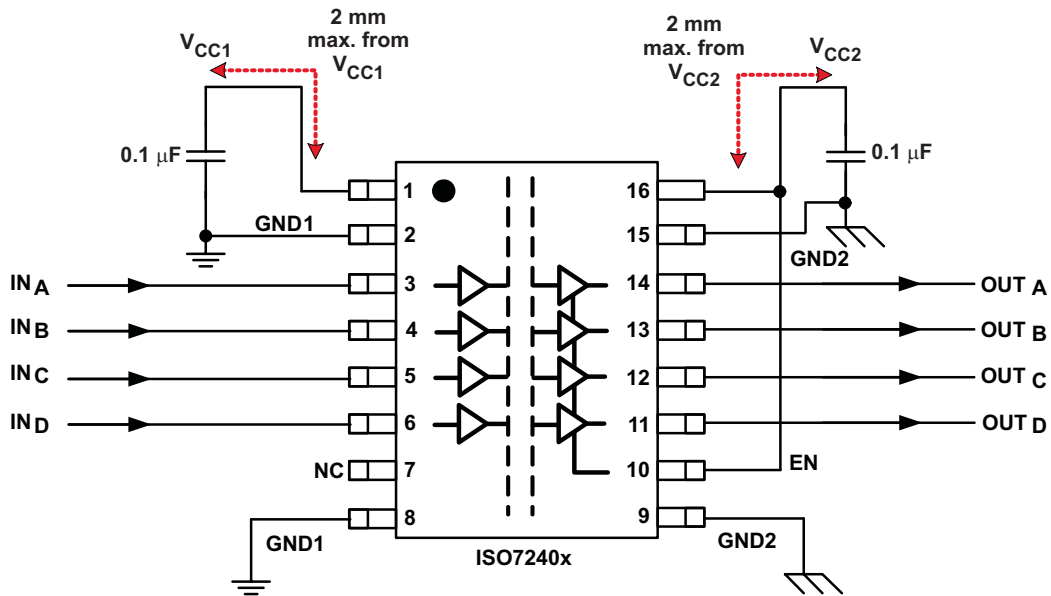


Figure 15. Typical ISO7240x Application Circuit

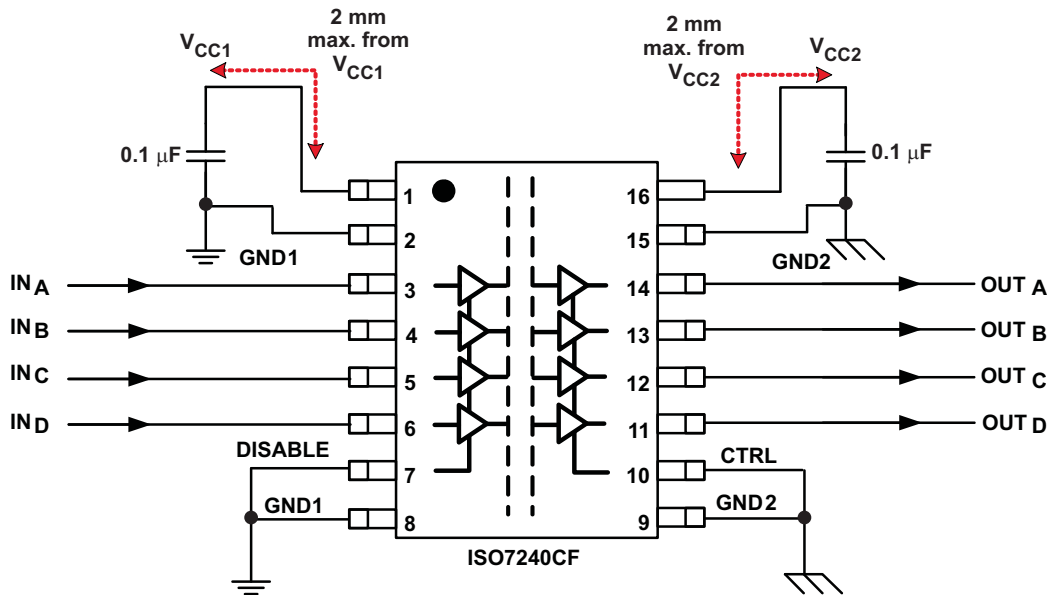
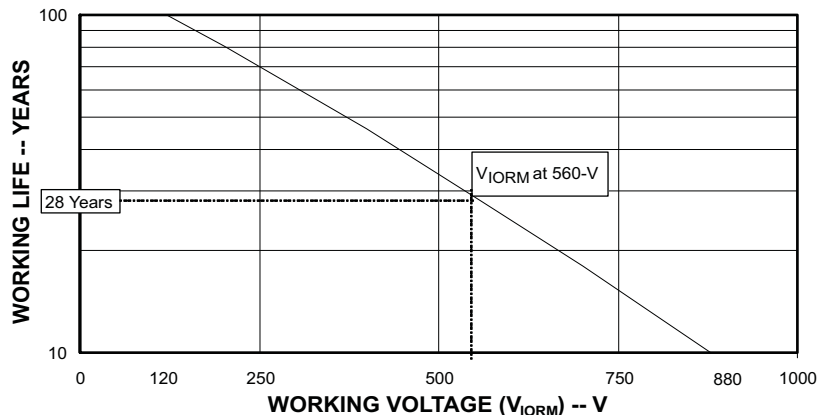


Figure 16. Typical ISO7240CF Failsafe-Low Application Circuit

**LIFE EXPECTANCY vs WORKING VOLTAGE**



**Figure 17. Time-Dependant Dielectric Breakdown Testing Results**

**PACKAGING INFORMATION**

| Orderable Device | Status<br>(1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan<br>(2)         | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples                 |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| ISO7240CFQDWRQ1  | ACTIVE        | SOIC         | DW              | 16   | 2000        | Green (RoHS & no Sb/Br) | NIPDAU                  | Level-3-260C-168 HR  | -40 to 125   | ISO7240CFQ              | <a href="#">Samples</a> |
| ISO7241CQDWRQ1   | ACTIVE        | SOIC         | DW              | 16   | 2000        | Green (RoHS & no Sb/Br) | NIPDAU                  | Level-3-260C-168 HR  | -40 to 125   | ISO7241CQ               | <a href="#">Samples</a> |
| ISO7242CQDWRQ1   | ACTIVE        | SOIC         | DW              | 16   | 2000        | Green (RoHS & no Sb/Br) | NIPDAU                  | Level-3-260C-168 HR  | -40 to 125   | ISO7242CQ               | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF ISO7240CF-Q1, ISO7241C-Q1, ISO7242C-Q1 :**

- Catalog: [ISO7240CF](#), [ISO7241C](#), [ISO7242C](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

| Device          | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| ISO7240CFQDWRQ1 | SOIC         | DW              | 16   | 2000 | 330.0              | 16.4               | 10.75   | 10.7    | 2.7     | 12.0    | 16.0   | Q1            |
| ISO7241CQDWRQ1  | SOIC         | DW              | 16   | 2000 | 330.0              | 16.4               | 10.75   | 10.7    | 2.7     | 12.0    | 16.0   | Q1            |
| ISO7242CQDWRQ1  | SOIC         | DW              | 16   | 2000 | 330.0              | 16.4               | 10.75   | 10.7    | 2.7     | 12.0    | 16.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device          | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| ISO7240CFQDWRQ1 | SOIC         | DW              | 16   | 2000 | 350.0       | 350.0      | 43.0        |
| ISO7241CQDWRQ1  | SOIC         | DW              | 16   | 2000 | 350.0       | 350.0      | 43.0        |
| ISO7242CQDWRQ1  | SOIC         | DW              | 16   | 2000 | 350.0       | 350.0      | 43.0        |



## GENERIC PACKAGE VIEW

**DW 16**

**SOIC - 2.65 mm max height**

7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4224780/A



DW0016B

# PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



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NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

DW0016B

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:4X



SOLDER MASK DETAILS

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NOTES: (continued)

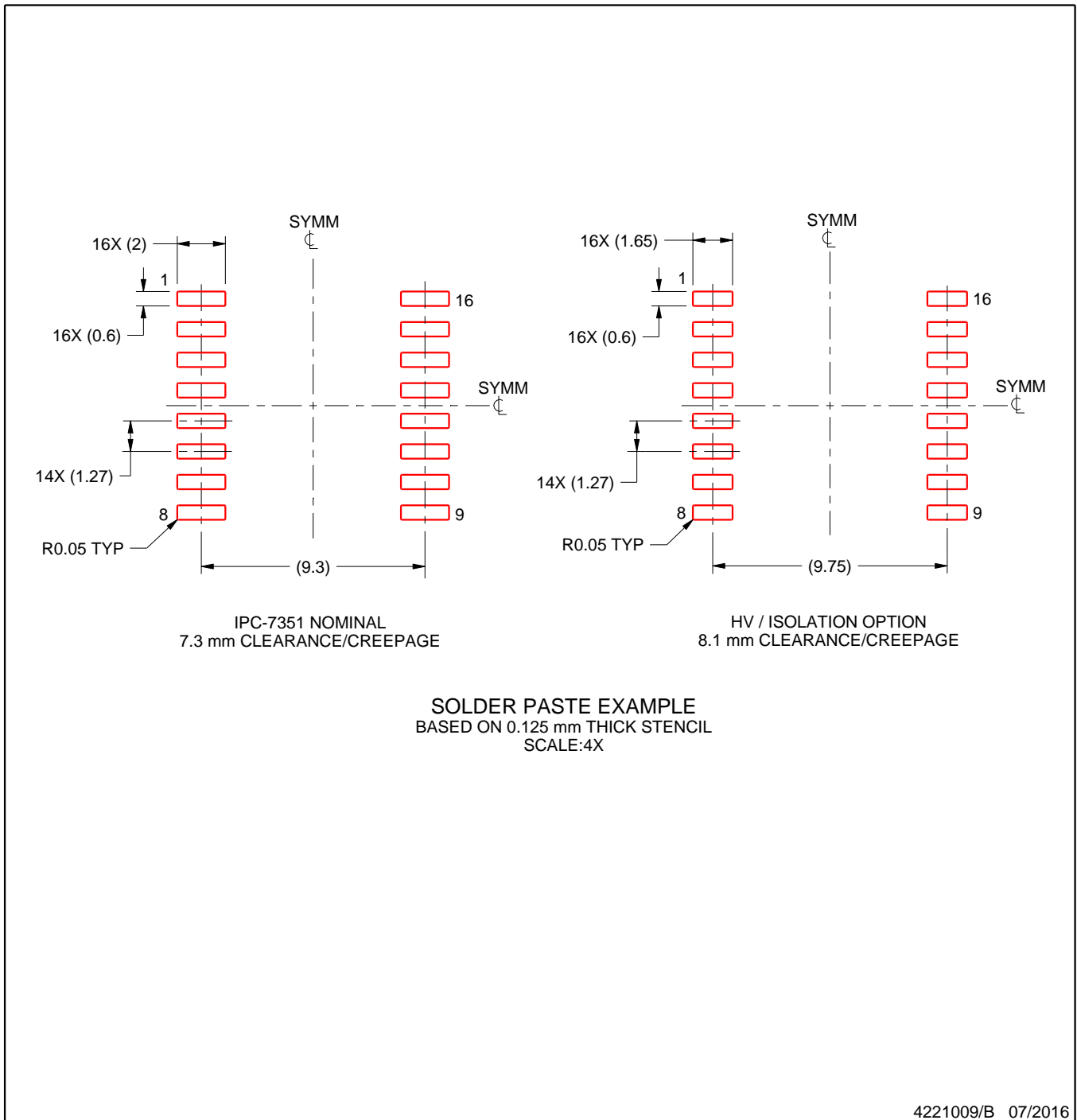
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0016B

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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